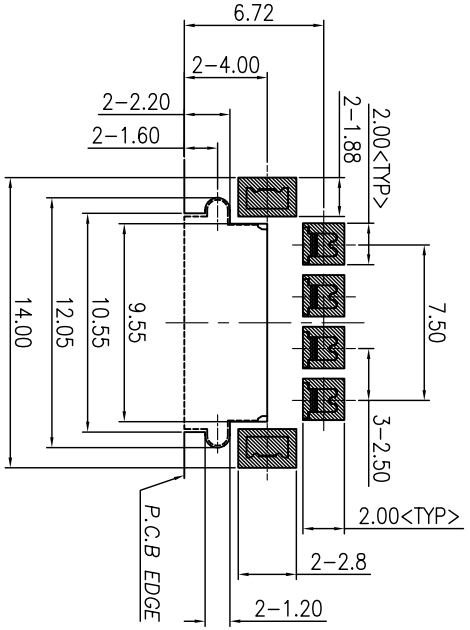
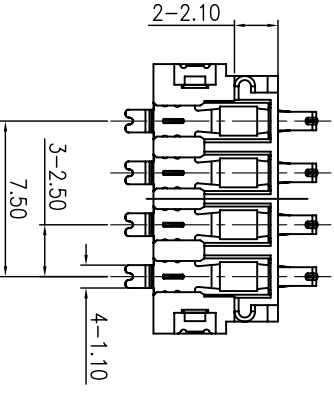
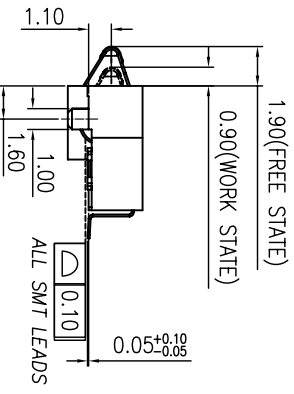
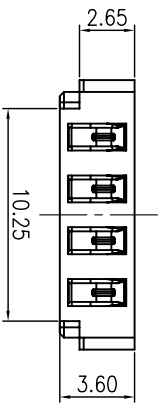
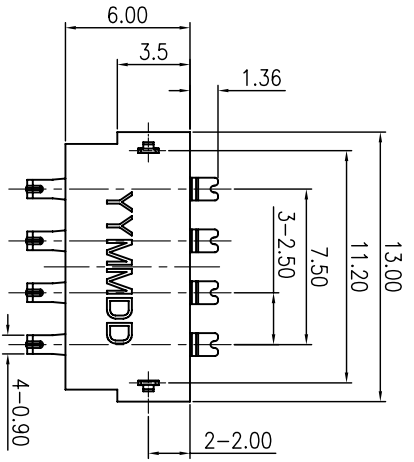
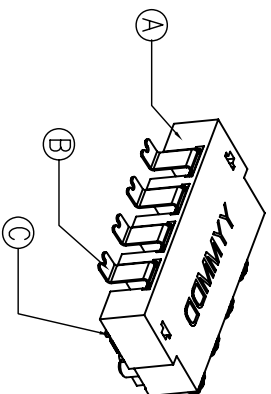


REV.	ECN NO. OR DESCRIPTION	REVISED	DATE
A	INITIAL RELEASE	胡重煥	2009.07.22



RECOMMENDED P.C.B. LAYOUT
TOP VIEW (TOLERANCE: ±0.05)

- NOTE:
- MATERIAL:
HOUSING: HIGE TEMP. THERMOPLASTIC; U194V-0, COLOR BLACK.
CONTACT: COPPER ALLOY, T=0.10;
TAB: COPPER ALLOY, T=0.20.
 - FINISH:
CONTACT:
10U" MIN GOLD PLATING ON CONTACT AREA;
1U" MIN GOLD PLATING ON SOLDER TAILS;
50U"~180U" NICKEL UNDERPLATING OVERALL.
TAB:
40U" MIN HIGH TEMP. TIN PLATING ALL OVER;
20U" MIN NICKEL UNDERPLATING OVERALL.
 - SPECIFICATION: SEE "2.5mm PITCH BATTERY 4PIN 4.0H PRODUCT SPEC."
 - SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ●
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING: ●
 - FOR REFLOW SOLDERING LEAD FREE PROCESS.
 - D/C DESCRIPTION: YYMMDD
DAY MONTH YEAR



C	TAB	2	COPPER ALLOY, 0.20T	TIN OVER NICKEL
B	CONTACT	4	COPPER ALLOY, 0.10T	GOLD ON CONTACT AREA
A	HOUSING	1	H-TEMP THERMOPLASTIC U194V-0	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信登企業股份有限公司

DECIMALS:	ANGLES:	TITLE	SCALE	UNIT:	REV:
X : ±0.5	X : ±2°	DWN 胡重煥	4:1	mm	1
X.X : ±0.3	X.X : ±1'	CHKD 劉木達			
X.XX : ±0.2		APVD 羅文生			

CUSTOMER COPY

